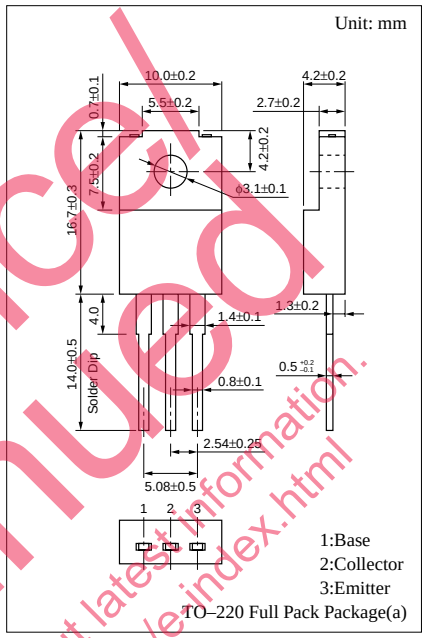
2SD1475

Silicon NPN triple diffusion planar type

For power switching



Features

- High-speed switching
- Satisfactory linearity of foward current transfer ratio h_{FE}
- Large collector power dissipation P_C
- Full-pack package which can be installed to the heat sink with one screw

Absolute Maximum Ratings (T_C=25˚C)

Parameter		Symbol	Ratings	Unit
Collector to base voltage		V_{CBO}	80	V
Collector to emitter voltage		V_{CEO}	60	V
Emitter to base voltage		V_{EBO}	6	V
Peak collector current		I_{CP}	8	A
Collector current		I_C	4	A
Base current		I_B	1	A
Collector power dissipation	T_C=25°C	P_C	35	W
	Ta=25°C		2	
Junction temperature		T_j	150	˚C
Storage temperature		T_{stg}	–55 to +150	˚C

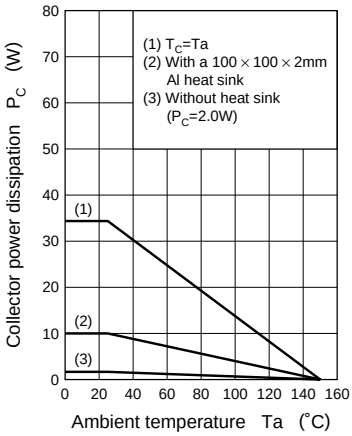
Electrical Characteristics (T_C=25˚C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	V_{CB} = 80V, I_E = 0			100	µA
Emitter cutoff current	I_{EBO}	V_{EB} = 6V, I_C = 0			100	µA
Collector to emitter voltage	V_{CEO}	I_C = 25mA, I_B = 0	60			V
Forward current transfer ratio	h_{FE1}	V_{CE} = 4V, I_C = 1A	70		320	
	h_{FE2}	V_{CE} = 4V, I_C = 3A	20			
Base to emitter voltage	V_{BE}	V_{CE} = 4V, I_C = 1A			1.2	V
Collector to emitter saturation voltage	$V_{CE(sat)}$	I_C = 2A, I_B = 0.2A			1	V
Transition frequency	f_T	V_{CE} = 12V, I_C = 0.2A, f = 10MHz		50		MHz
Turn-on time	t_{on}	I_C = 4A, I_{B1} = 0.4A, I_{B2} = – 0.4A, V_{CC} = 50V		0.35		µs
Storage time	t_{stg}			1		µs
Fall time	t_f			0.3		µs

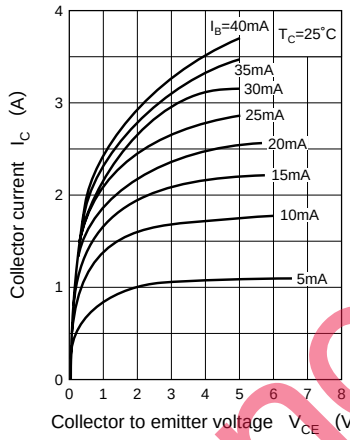
*h_{FE1} Rank classification

Rank	Q	P	O
h_{FE1}	70 to 150	120 to 250	160 to 320

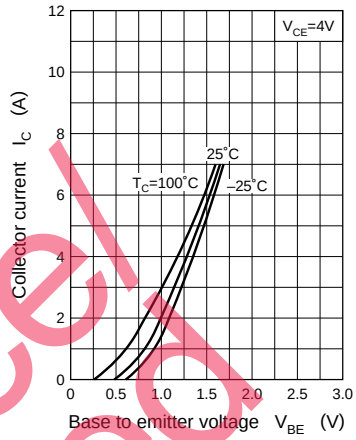
P_C — Ta



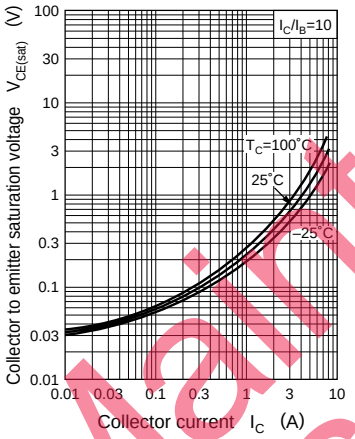
I_C — V_{CE}



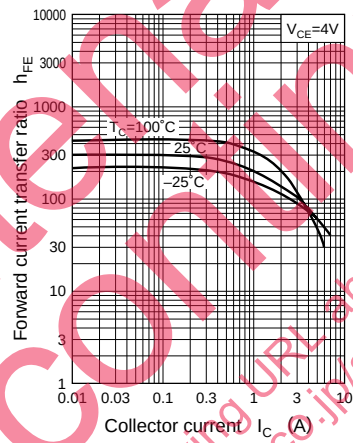
I_C — V_{BE}



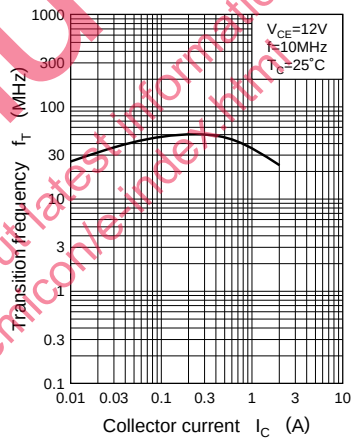
$V_{CE(sat)}$ — I_C



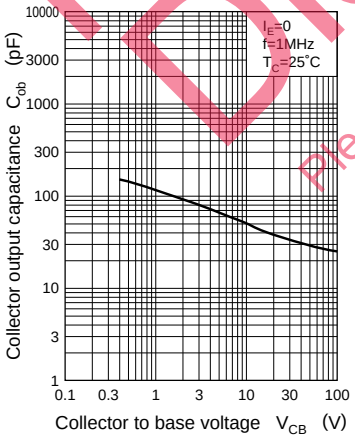
h_{FE} — I_C



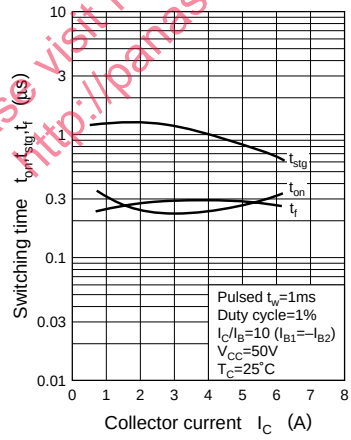
f_T — I_C



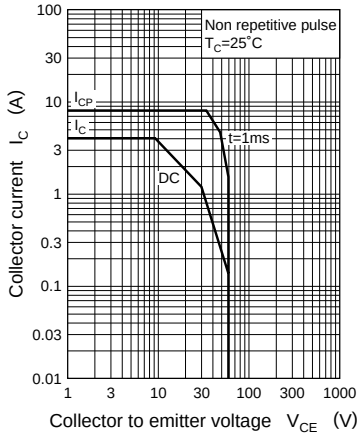
C_{ob} — V_{CB}



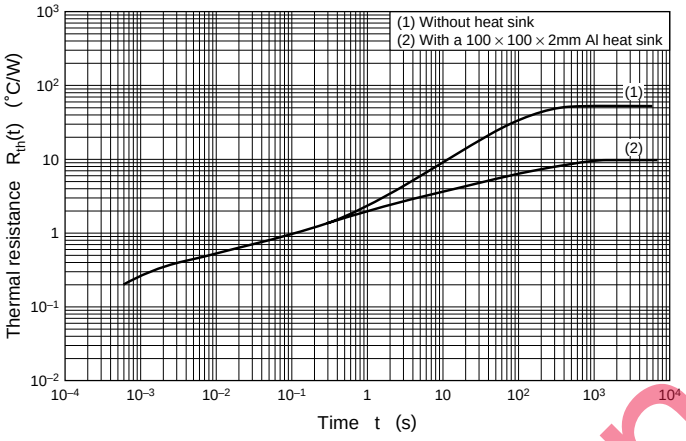
t_{on}, t_{stg}, t_f — I_C



Area of safe operation (ASO)



$R_{th(t)}$ — t



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